

ABSTRACT

The present invention provides an aqueous composition useful for polishing copper interconnects on a semiconductor wafer comprising by weight percent up to 25 oxidizer, 0.05 to 1 inhibitor for a nonferrous metal, 0.01 to 5 complexing agent for the nonferrous metal, 0.01 to 5 modified cellulose, and balance water, wherein the composition is free of polyacrylic acid, the amount of modified cellulose providing a copper removal function and a wafer clear of copper.